

## **Custom Chip Fabrication Services**

### **Clean Room/Manufacturing Area Summary**

Approximately 3500 square feet of temperature/humidity controlled HEPA Clean Room environment consisting of the following:

575 sq ft Class 100 Lithography area (Yellow Room) containing Karl Suss 1000W MA150 cassette to cassette Proximity aligner (1 micron registration and resolution capability), ABM Custom Engineering 350W contact/proximity aligner (1 micron registration and resolution capability), Brewer Scientific CEE100 PhotoResist Spinner, and a Western Magnum Dry PhotoResist laminator;

425 sq ft Class 100 Bonding Room containing 6 foot Class 10 Laminar Flow station, custom CCTV ABM Bonding Aligner, Bright field/Dark field high resolution Olympus Metallurgical Microscope, multiple UltraTech Plate/Photomask Cleaners, and multiple Lindberg/Blue M stainless steel industrial size bonding ovens;

1000 sq ft Class 1000 Etch area containing multiple custom wet sinks with controlled temperature/filtered/recirculating/cascade etch baths, heated quartz baths, and misc tanks, multiple SemiTool resistivity controlled spin rinse dryers, multiple KLA-Tencor Alpha Step Profilometry systems, custom ASECO automated inspection system, and multiple high resolution Nikon manual inspection microscopes;

1500 sq ft Class 1000 Assembly area containing programmable automated Asymtek and PVA glue dispense systems, UV tunnels, custom automated labeling and bagging systems, and multiple Lindberg/Blue M stainless steel ovens.

Additional non-clean room areas contain multiple Disco Precision Dicing saws, multiple Lindberg/Blue M 1200 degree C box furnaces, MRL custom 1300 degree C tube furnace with controlled atmosphere, and multiple programmable CNC micro drilling systems.

Facility fully permitted and compliant with all Local, State, and Federal Hazardous Materials, Hazardous Waste, Waste Water, and Environmental regulations. Also ISO9001:2000 certified.